

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16143	
1.3 Title of PCN	TSHT (China) additional back-end qualification for 1Kb, 2Kb, 4Kb and 16Kb I <sup>2</sup> C EEPROM in SO8N	
1.4 Product Category	M24C01, M24C02, M24C04 and M24C16 EEPROM products in SO8N	
1.5 Issue date	2026-02-04	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	David RICETTO
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Finishing (SOP 2617)	N/A

**4. Description of change**

	<b>Old</b>	<b>New</b>
4.1 Description	The M24C01, M24C02, M24C04 and M24C16 currently assembled in SO8N and tested at ST Shenzhen (China)...	...will be also assembled & tested at TSHT (China) subcontractor.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: Marking change - Fit: no change - Function: no change	

**5. Reason / motivation for change**

5.1 Motivation	The strategy of the STMicroelectronics Memory division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the TSHT back-end assembly & test site as a second source will allow us to increase capacity and reinforce long term competitiveness.
5.2 Customer Benefit	DOUBLE SOURCING

**6. Marking of parts / traceability of change**

6.1 Description	Assembly plant identifier "9" on SO8N package top marking
-----------------	---

**7. Timing / schedule**

7.1 Date of qualification results	2026-02-03
7.2 Intended start of delivery	2026-05-08
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

8.1 Description	16143 RRCS2505 Reliability report F8H SO8N TSHT CuPd.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	<b>Issue Date</b>	2026-02-04

**9. Attachments (additional documentations)**

16143 Public product.pdf  
16143 PCN TSHT ALL CUSTOMERS LOW DENSITIES I2C F8H+ .pdf  
16143 RRCS2505 Reliability report F8H SO8N TSHT CuPd.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24C01-RMN6TP	
	M24C02-RMN6TP	
	M24C02-WMN6TP	

## **IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved